

TRIACs, 16A

Snubberless, Logic Level and Standard

Features

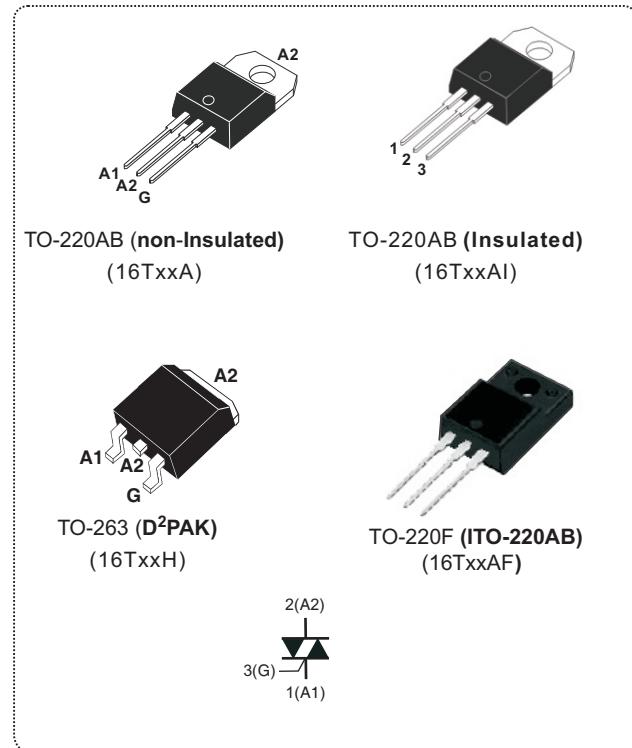
- Medium current Triac
- Low thermal resistance with clip bonding
- Low thermal resistance insulation ceramic for insulated 16T
- High commutation (4Q) or very high commutation (3Q) capability
- RoHS compliant, UL certified (File NO:E320098)
- Insulated tab (16TxxAI series, rated at 2500 V_{RMS})

Applications

- Snubberless versions (With Suffix W) especially recommended for use on inductive loads, because of their high commutation performances
- On/off or phase angle function in applications such as static relays, light dimmers and appliance motor speed controllers

Description

Available either in through-hole or surface-mount packages, the 16TxxA and 16TxxAI triacs series are suitable for general purpose mains power AC switching



SYMBOL	VALUE	UNIT
I _{T(RMS)}	16	A
V _{DRM/V_{RRM}}	600 to 1000	V
I _{GT(Q1)}	5 to 50	mA

Device summary			
SYMBOL	PARAMETER	16TxxAI ⁽¹⁾	16TxxA
I _{T(RMS)}	On-state RMS current	16	16
V _{DRM/V_{RRM}}	Repetitive peak off-state voltage	600/800/1000	600/800/1000
I _{GT(Snubberless)}	Triggering gate current	35/50	35/50
I _{GT(Logic level)}	Triggering gate current	10	10
I _{GT(Standard)}	Triggering gate current	25/50	25/50

Note 1: Insulated

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS			VALUE	UNIT
RMS on-state current (full sine wave)	$I_{T(RMS)}$	TO-220/TO-263		$T_c = 100^\circ C$	16	A
Non repetitive surge peak on-state current (full cycle, T_j initial = 25°C)		TO-220insulate/TO-220F (ITO-220AB)		$T_c = 86^\circ C$		
I^2t Value for fusing	I_{TSM}	$F = 50$ Hz		$t = 20$ ms	160	A
		$F = 60$ Hz		$t = 16.7$ ms	168	
I^2t Value for fusing	I^2t	$t_p = 10$ ms			128	A^2s
Critical rate of rise of on-state current $I_G = 2xI_{GT}$, $t_f \leq 100$ ns	dI/dt	$F = 100$ Hz		$T_j = 125^\circ C$	50	$A/\mu s$
Peak gate current	I_{GM}	$T_p = 20$ μs		$T_j = 125^\circ C$	4	A
Average gate power dissipation	$P_{G(AV)}$	$T_j = 125^\circ C$			1	W
Storage temperature range	T_{stg}				- 40 to 150	${}^\circ C$
Operating junction temperature range	T_j				- 40 to 125	

◎ ELECTRICAL CHARACTERISTICS ($T_j = 25^\circ C$ unless otherwise specified)
SNUBBERLESS and Logic level (3 quadrants)

SYMBOL	TEST CONDITIONS	QUADRANT		16Txxxx			Unit
				SW	CW	BW	
$I_{GT}^{(1)}$	$V_D = 12$ V, $R_L = 33\Omega$	I - II - III	MAX.	10	35	50	mA
V_{GT}		I - II - III	MAX.	1.3			V
V_{GD}	$V_D = V_{DRM}$, $R_L = 3.3K\Omega$ $T_j = 125^\circ C$	I - II - III	MIN.	0.2			V
$I_H^{(2)}$	$I_T = 500$ mA		MAX.	15	40	55	mA
I_L	$I_G = 1.2 I_{GT}$	I - III	MAX.	25	50	70	mA
		II		30	60	80	
$dV/dt^{(2)}$	$V_D = 67\% V_{DRM}$, gate open, $T_j = 125^\circ C$		MIN.	40	500	1000	V/ μs
$(dI/dt)c^{(2)}$	$(dV/dt)c = 0.1$ V/ μs	$T_j = 125^\circ C$	MIN.	8.5	-	-	A/ms
	$(dV/dt)c = 10$ V/ μs	$T_j = 125^\circ C$		3	-	-	
	Without snubber	$T_j = 125^\circ C$		-	8.5	14	

Note 1: Minimum I_{GT} is guaranteed at 5% of I_{GT} max.

Note 2: For both polarities of A2 referenced to A1.

◎ ELECTRICAL CHARACTERISTICS ($T_j = 25^\circ C$ unless otherwise specified)
Standard (4 quadrants)

SYMBOL	TEST CONDITIONS	QUADRANT		16Txxxx		UNIT
				C	B	
$I_{GT}^{(1)}$	$V_D = 12$ V, $R_L = 33\Omega$	I - II - III	MAX.	25	50	mA
		IV		50	100	
V_{GT}		ALL		1.3		V
V_{GD}	$V_D = V_{DRM}$, $R_L = 3.3K\Omega$, $T_j = 125^\circ C$	ALL		0.2		V
$I_H^{(2)}$	$I_T = 500$ mA		MAX.	25	50	mA
I_L	$I_G = 1.2 I_{GT}$	I - III - IV	MAX.	40	60	mA
		II		80	120	
$dV/dt^{(2)}$	$V_D = 67\% V_{DRM}$, gate open, $T_j = 125^\circ C$		MIN.	200	400	V/ μs
$(dV/dt)c^{(2)}$	$(dI/dt)c = 7$ A/ms, $T_j = 125^\circ C$		MIN.	5	10	V/ μs

STATIC CHARACTERISTICS					
SYMBOL	TEST CONDITIONS			VALUE	UNIT
V _{TM} ⁽²⁾	I _{TM} = 22.5 A, t _P = 380 µs	T _j = 25°C	MAX.	1.55	V
V _{t0} ⁽²⁾	Threshold voltage	T _j = 125°C	MAX.	0.85	V
R _d ⁽²⁾	Dynamic resistance	T _j = 125°C	MAX.	25	mΩ
I _{DRM} I _{RRM}	V _D = V _{DRM} V _R = V _{RRM}	T _j = 25°C T _j = 125°C	MAX.	5	µA
				1	mA

Note 1: Minimum I_{GT} is guaranteed at 5% of I_{GT} max.

Note 2: For both polarities of A2 referenced to A1.

THERMAL RESISTANCE					
SYMBOL				VALUE	UNIT
R _{th(j-c)}	Junction to case (AC)		TO-220AB, D ² PAK	1.2	°C/W
			TO-220AB Insulated, TO-220F	2.1	
R _{th(j-a)}	Junction to ambient		D ² PAK	45	°C/W
			TO-220AB Insulated, TO-220AB, TO-220F	60	

Note 1: S=Copper surface under tab

PRODUCT SELECTOR						PACKAGE	
PART NUMBER	VOLTAGE (xx)			SENSITIVITY	TYPE		
	600 V	800 V	1000 V				
16TxxA-B/16TxxAl-B	V	V	V	50 mA	Standard	TO-220AB	
16TxxA-BW/16TxxAl-BW	V	V	V	50 mA	Snubberless		
16TxxA-C/16TxxAl-C	V	V	V	25 mA	Standard		
16TxxA-CW/16TxxAl-CW	V	V	V	35 mA	Snubberless		
16TxxA-SW/16TxxAl-SW	V	V	V	10 mA	Logic level		
16TxxH-B	V	V	V	50 mA	Standard	D ² PAK	
16TxxH-C	V	V	V	25 mA	Standard		
16TxxH-SW	V	V	V	10 mA	Logic level		
16TxxH-CW	V	V	V	35 mA	Snubberless		
16TxxH-BW	V	V	V	50 mA	Snubberless		
16TxxAF-B	V	V	V	50 mA	Standard	TO-220F (ITO-220AB)	
16TxxAF-C	V	V	V	25 mA	Standard		
16TxxAF-SW	V	V	V	10 mA	Logic level		
16TxxAF-CW	V	V	V	35 mA	Snubberless		
6TxxAF-BW	V	V	V	50 mA	Snubberless		

ORDERING INFORMATION					
ORDERING TYPE	MARKING	PACKAGE	WEIGHT	BASE Q'TY	DELIVERY MODE
16TxxA-yy	16TxxA-yy	TO-220AB	2.0g	50	Tube
16TxxAl-yy	16TxxAl-yy	TO-220AB (insulated)	2.3g	50	Tube
16TxxAF-yy	16TxxAF-yy	TO-220F(ITO-220AB)	2.5g	50	Tube
16TxxH-yy	16TxxH-yy	TO-236(D ² PAK)	2.0g	50	Tube

Note: xx = voltage, yy = sensitivity

ORDERING INFORMATION SCHEME

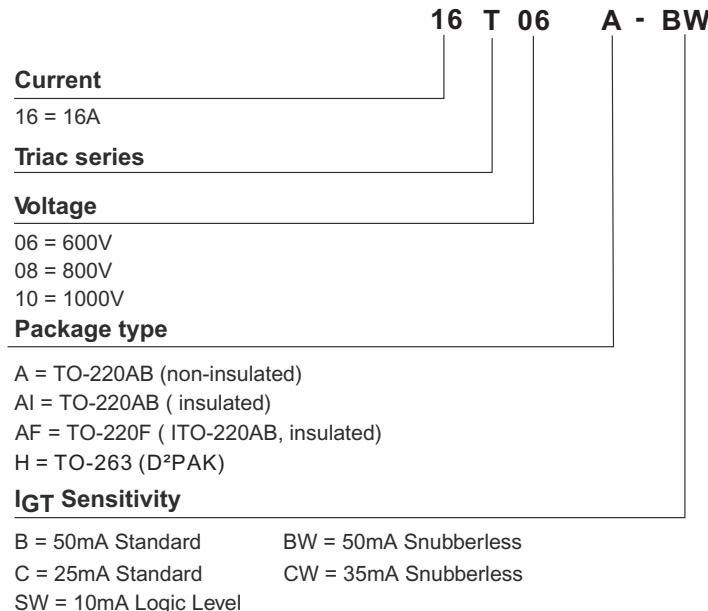


Fig.1 Maximum power dissipation versus on-state rms current (full cycle)

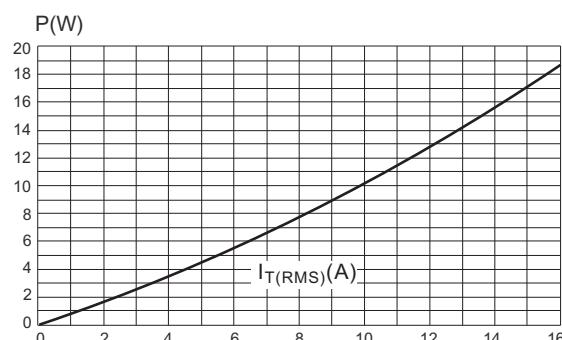


Fig.2 On-state rms current versus case temperature (full cycle)

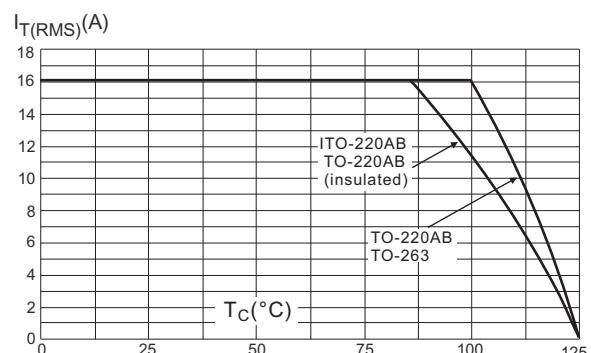


Fig.3 On-state current versus ambient temperature (full cycle)

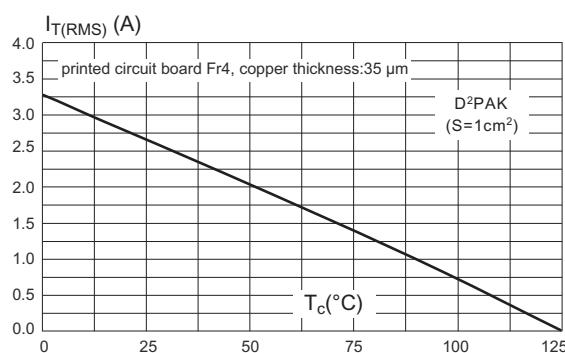


Fig.4 Relative variation of thermal impedance versus pulse duration

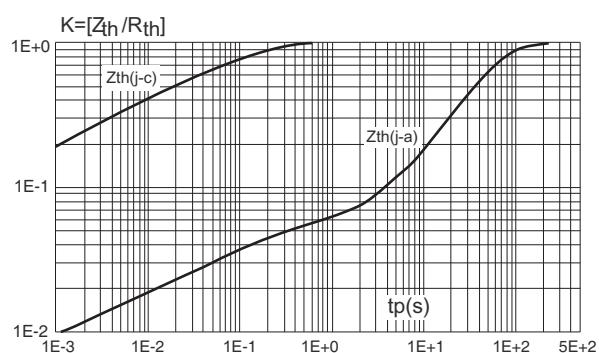


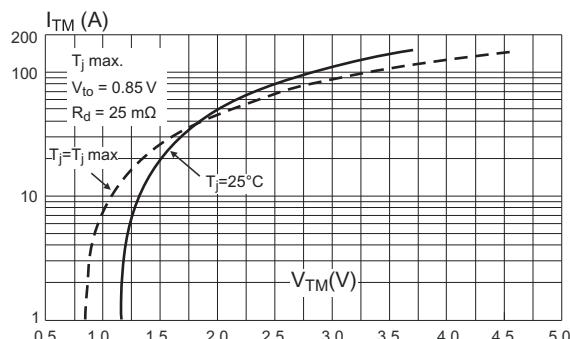
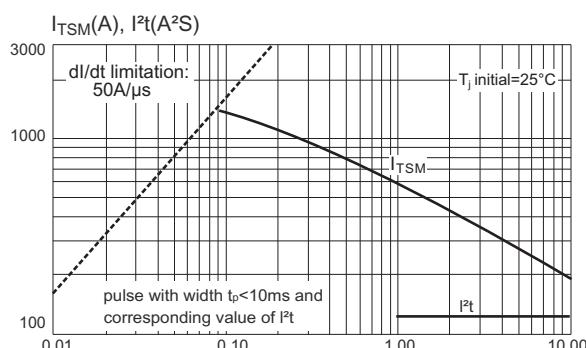
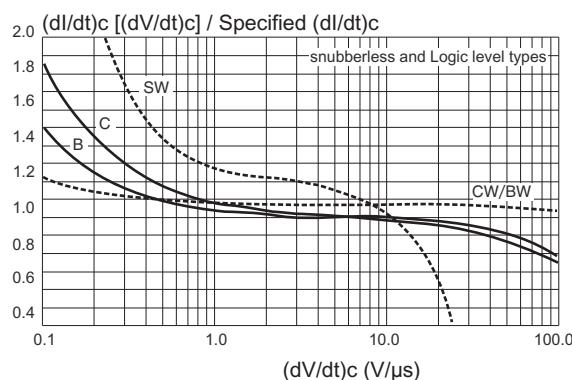
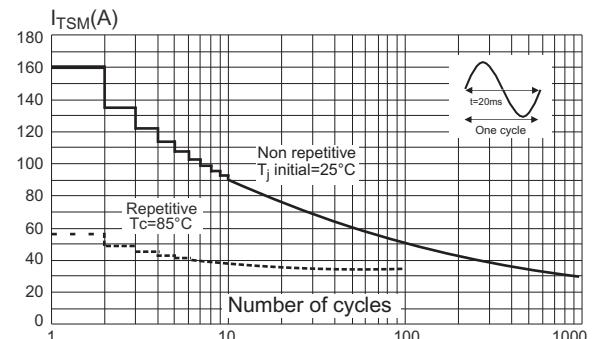
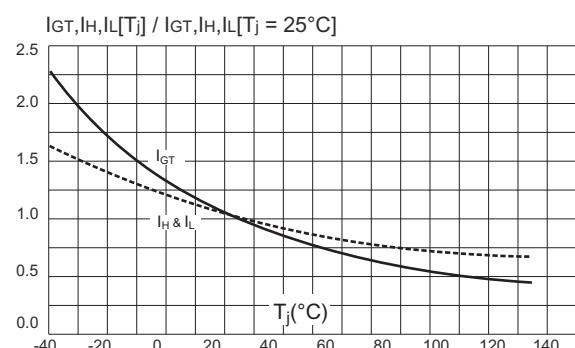
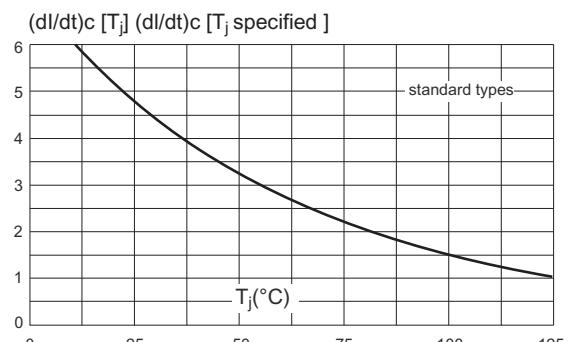
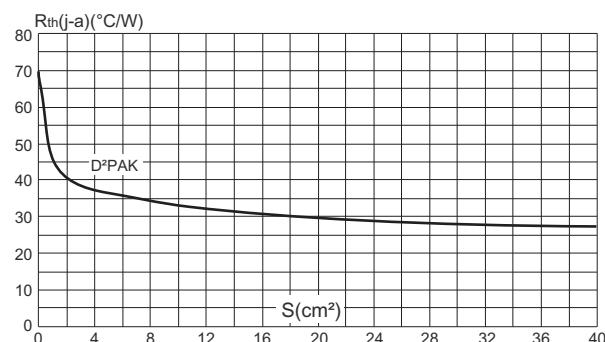
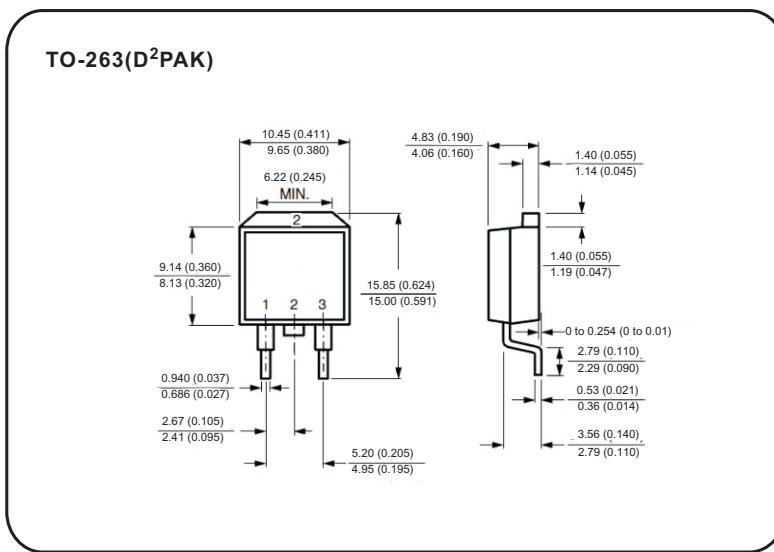
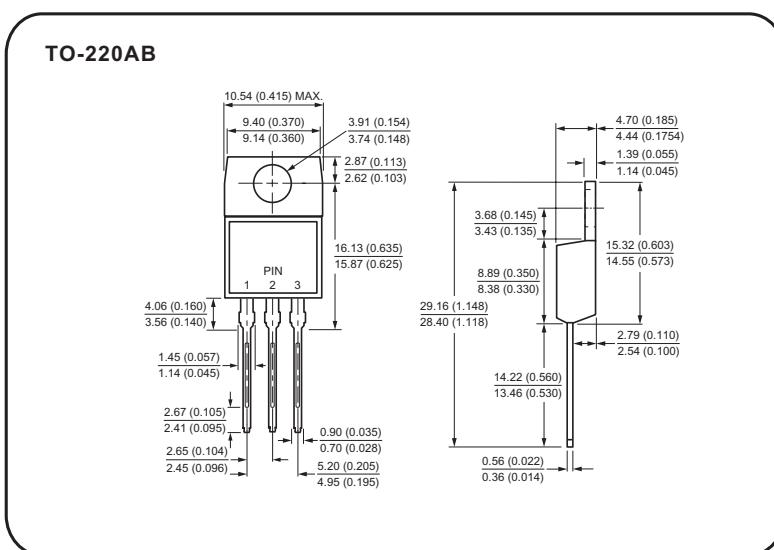
Fig.5 On-state characteristics (maximum values)

Fig.7. Non-repetitive surge peak on-state current for a sinusoidal

Fig.9 Relative variation of critical rate of decrease of main current versus (dV/dt)c (typical values)

Fig.6 surge peak on- state current versus number of cycles

Fig.8 Relative variation of gate trigger current

Fig.10 Relative variation of critical rate of decrease of main current versus (dV/dt)c (typical values)


Fig.11 D²PAK thermal resistance junction to ambient versus copper surface under tab (printed circuit FR4, copper thickness: 35µm)



Case Style



All dimensions in millimeters(inches)

Case Style

